



Material Content Data Sheet



Sales Product Name		TLS115B0LD		Issued		16. July 2019		
MA#		MA005350788						
Package		PG-TSON-10-2		Weight*		31.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.123	3.54	3.54	35367	35367
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8357	
wire	non noble metal	copper	7440-50-8	10.773	33.93	34.82	339324	348203
	non noble metal	copper	7440-50-8	0.032	0.10	0.10	1009	1009
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.12		1175
plastics	plastics	epoxy resin	-	1.922	6.05		60528	
	inorganic material	silicondioxide	60676-86-0	16.698	52.59	58.76	525949	587652
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11657	11657
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2024	2024
glue	plastics	epoxy resin	-	0.112	0.35		3522	
	noble metal	silver	7440-22-4	0.335	1.06	1.41	10566	14088
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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